SUPPLIER

URL for Additional Information

 PART INFORMATION

 Mfg Item Number
 KK22FN256CAH12R

 Mfg Item Name
 WLCSP 64 3.4*3.3*0.6P0.4

Company Name

Company Unique ID

Response Date

Page Date

Company Unique ID

Response Date

Company Unique ID

Company Unique

00HVA1.1 Response Document ID Contact Name Freescale Semiconductor Inc Contact Title Product Technical Support **Contact Phone** 1-800-521-6274 Contact Email support@freescale.com **Authorized Representative** Daniel Binyon Representative Title **EPP Customer Response** Representative Phone 512-895-3406 Representative Email eppanlst@freescale.com

DECLARATION

EU RoHS
Pb Free
HalogenFree
Plating Indicator
EU RoHS Exemption(s)

www.freescale.com

MANUFACTURING Mfg Item Number KK22FN256CAH12R WLCSP 64 3.4*3.3*0.6P0.4 Mfg Item Name Version ALL Weight 0.013700 UoM EACH Unit Volume J-STD-020 MSL Rating Peak Processing Temperature 260 C Max Time at Peak Temperature 40 seconds Number of Processing Cycles 3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Co
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight
Exemptions	6(b): Lead as an alloying element in aluminium containing up to 0.4% lead by weight
	6(c): Copper alloy containing up to 4% lead by weight
	7(a): Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
	7(b): Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications
	7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
	7(c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
	7(c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC
	7(c)-IV: Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors
	15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight				SubstanceWeight	UoM	SubPart PPM		ARTICLEPPM	ARTICLE%
Solder Balls - Lead Free	0.0038					g				
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8	0	g	0	0	0	0
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4	0.00006343	g	16692	1.6692	4629	0.4629
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5	0.00373657	g	983308	98.3308	272742	27.2742
RCP build up	0.0005					g				
RCP build up		Plastics/polymers	Plastic: PI - Polyimide	-	0.00033333	g	666667	66.6667	24330	2.433
RCP build up		Plastics/polymers	1-Methoxy-2-propyl acetate	108-65-6	0.00016667	g	333333	33.3333	12165	1.2165
Silicon Semiconductor Die	0.0094					g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-	0.000188	g	20000	2	13722	1.3722
Silicon Semiconductor Dio		Glass	Silicon doned		0.000212	0	080000	QR	672412	67 2412

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http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

LINKS TO BLANK IPC1752 FORMS Blank IPC1752 v1.1 Form IPC1752 XML LINKS

http://www.freescale.com/mcds/KK22FN256CAH12R_IPC1752_v11.xml

http://www.freescale.com/mcds/KK22FN256CAH12R_IPC1752A.xml